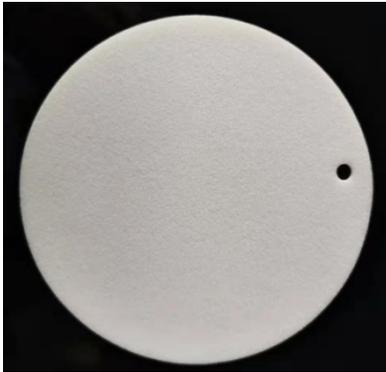


## General Information

### CMP 800 Polishing Pad

Product Part #: SH-Q13-800

Product Description: Aluminum Oxide CMP Pad



CMP-800 CMP pad is a **hard surface pad** replicated with 3D technology.

CMP-800 can be used as sub pad in CMP process.

## Material Specification

<b>Pad Surface Parameter</b>	Product Name	Aluminum Oxide CMP Pad
	Pad Density (g/mm <sup>3</sup> )	0.38 +/- 0.03
	Pad Hardness (Shore A)	78 +/-3
	Pad Thickness (mm)	1.37 +/-0.05
	Groove Pattern (mm)	-
	Groove Width (mm)	-
	Groove Depth (mm)	-
	Outer Diameter	(cut per customer requirement)
<b>Appearance</b>	Surface tear off	Not allow
	Fold mark	Not allow

## Main Features for CMP-800 Pad

- Offer higher stock removal.
- Suitable for silicon wafer surface removal.
- Able to work with Silicon Oxide base slurry.